



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLD1114-1EP	Issued	24. June 2021
MA#	MA005555328		
Package	PG-TSDSO-14-13	Weight*	64.05 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.713	2.67	2.67	26739	26739
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		146	
	non noble metal	zinc	7440-66-6	0.037	0.06		583	
	non noble metal	iron	7439-89-6	0.746	1.17		11653	
	non noble metal	copper	7440-50-8	30.306	47.32	48.56	473178	485560
wire	non noble metal	copper	7440-50-8	0.096	0.15	0.15	1503	1503
encapsulation	organic material	carbon black	1333-86-4	0.086	0.13		1349	
	plastics	epoxy resin	-	3.370	5.26		52617	
	inorganic material	silicondioxide	60676-86-0	25.347	39.58	44.97	395751	449717
leadfinish	non noble metal	tin	7440-31-5	1.644	2.57	2.57	25670	25670
plating	noble metal	silver	7440-22-4	0.135	0.21	0.21	2106	2106
glue	plastics	epoxy resin	-	0.139	0.22		2176	
	noble metal	silver	7440-22-4	0.418	0.65	0.87	6529	8705
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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